

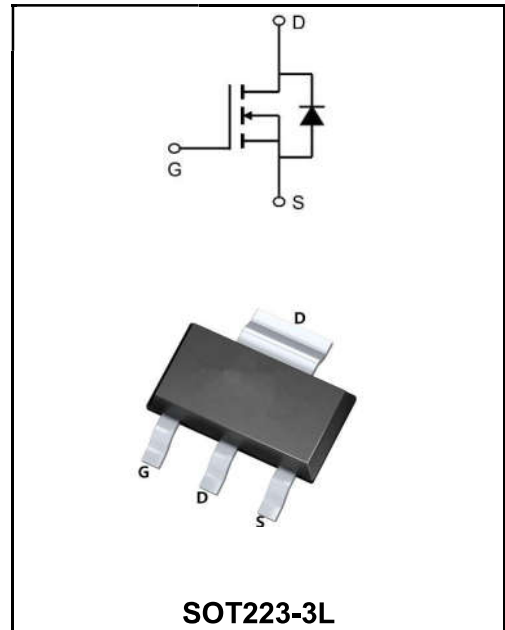
100V N-CHANNEL ENHANCEMENT MODE MOSFET

MAIN CHARACTERISTICS

I_D	8A
V_{DSS}	100V
R_{DS(on)-typ(@V_{GS}=10V)}	< 100mΩ (Type:88 mΩ)

Application

- ◆Automotive lighting
- ◆Load switch
- ◆Uninterruptible power supply



Product Specification Classification

Part Number	Package	Marking	Pack
YFW8N10MSI	SOT-223	YFW 8N10MSI XXXXX	3000PCS/Tape

Maximum Ratings at T_c=25°C unless otherwise specified

Characteristics	Symbols	Value	Units
Drain-Source Voltage	V_{DS}	100	V
Gate - Source Voltage	V_{GS}	±20	V
Drain Current, V _{GS} @ 10V @T _C =25°C	I_D	8	A
Drain Current, V _{GS} @ 10V @T _C =100°C	I_D	6.5	A
Pulsed Drain Current ¹	I_{DM}	24	A
Total Power Dissipation @T _C =25°C	P_D	30	W
Total Power Dissipation ³ @T _A =25°C	P_D	2.7	W
Storage Temperature Range	T_{STG}	-55 to +150	°C
Operating Junction Temperature Range	T_J	-55 to +150	°C
Maximum Thermal Resistance, Junction ambient	R_{θJA}	100	°C/W
Maximum Thermal Resistance, Junction-case	R_{θJC}	5.1	°C/W

Maximum Ratings at Tc=25°C unless otherwise specified

Characteristics	Test Condition	Symbols	Min	Typ	Max	Units
Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	V(BR)DSS	100	107	-	V
Zero Gate Voltage Drain Current	$V_{DS}=100V, V_{GS}=0V$	I_{DSS}	-	-	1.0	μA
Gate to Body Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	I_{GSS}	-	-	±100	nA
Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	V_{GS(th)}	1.0	1.5	2.5	V
Static Drain-Source on-Resistance note3	$V_{GS}=10V, I_D=5A$	R_{DS(ON)}	-	88	110	mΩ
	$V_{GS}=4.5V, I_D=3A$		-	96	140	
Input Capacitance	$V_{DS}=25V$ $V_{GS}=0V$ $f=1.0MHz$	C_{iss}	-	765	-	pF
Output Capacitance		C_{oss}	-	38	-	
Reverse Transfer Capacitance		C_{rss}	-	33	-	
Total Gate Charge	$V_{DS}=30V$ $V_{GS}=10V$ $I_D=5A$	Q_g	-	12	-	nC
Gate-Source Charge		Q_{gs}	-	2.2	-	
Gate-Drain("Miller") Charge		Q_{gd}	-	2.5	-	
Turn-on delay time	$V_{DS}=30V$ $I_D=10A$ $R_G=1.8\Omega$ $V_{GS}=10V$	t_{d(on)}	-	7	-	ns
Turn-on Rise Time		T_r	-	5	-	
Turn-Off Delay Time		t_{d(OFF)}	-	16	-	
Turn-Off Fall Time		t_f	-	6	-	
Maximum Continuous Drain to Source Diode Forward Current		I_S	-	-	10	A
Maximum Pulsed Drain to Source Diode Forward Current		I_{SM}	-	-	40	A
Drain to Source Diode Forward Voltage	$V_{GS}=0V, I_S=10A$	V_{SD}	-	-	1.2	V
Body Diode Reverse Recovery Time	$I_F=1A, dI/dt=100A/\mu s$	t_{rr}	-	21	-	ns
Body Diode Reverse Recovery Charge		Q_{rr}	-	21	-	nC

Note :

- 1、 The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.
- 2、 The data tested by pulsed , pulse width $\cong 300\mu s$, duty cycle $\cong 2\%$
- 3、 The power dissipation is limited by 150°C junction temperature
- 4、 The data is theoretically the same as I D and I DM , in real applications , should be limited by total power dissipation.

Ratings and Characteristic Curves

Typical Characteristics

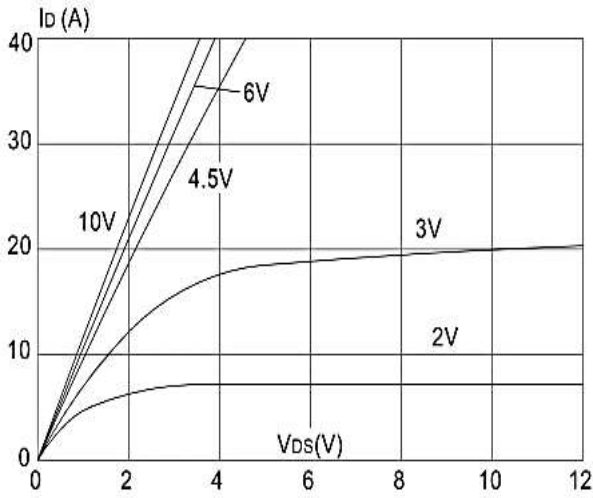


Figure 1: Output Characteristics

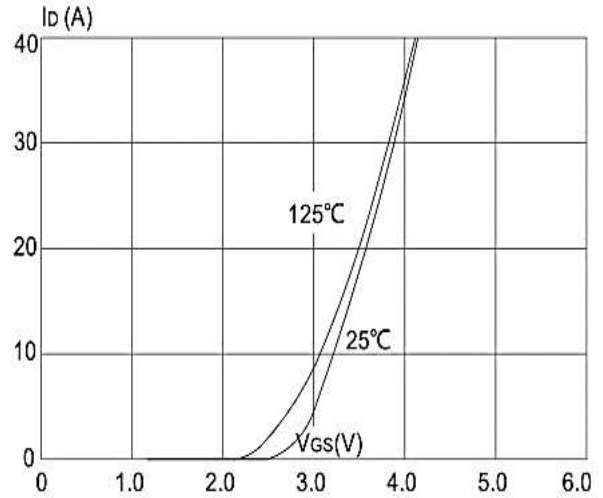


Figure 2: Typical Transfer Characteristics

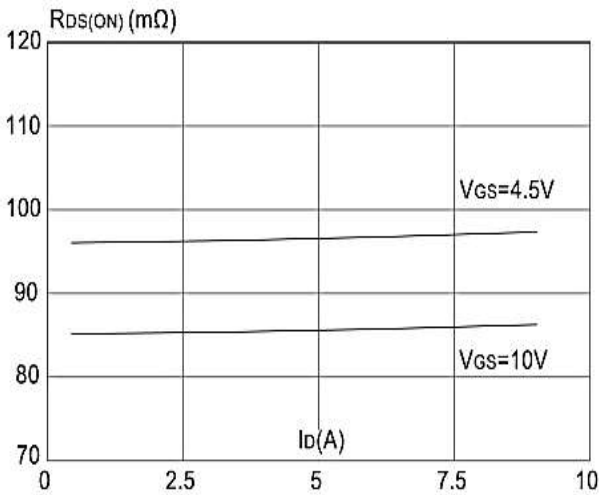


Figure 3: On-resistance vs. Drain Current

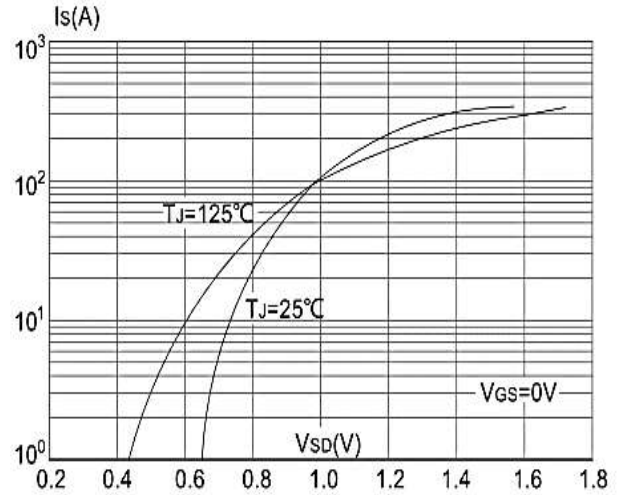


Figure 4: Body Diode Characteristics

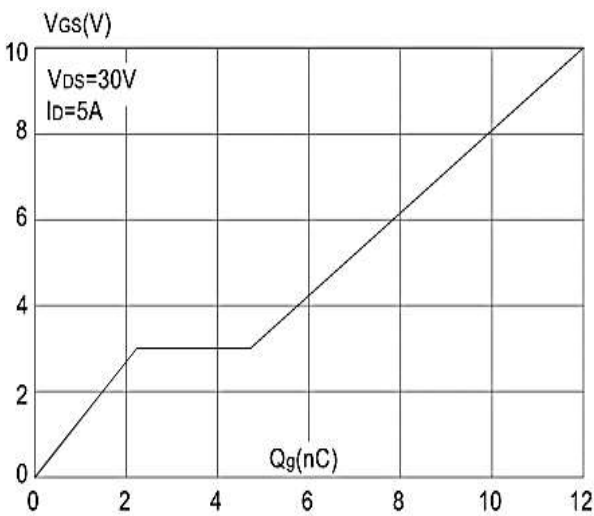


Figure 5: Gate Charge Characteristics

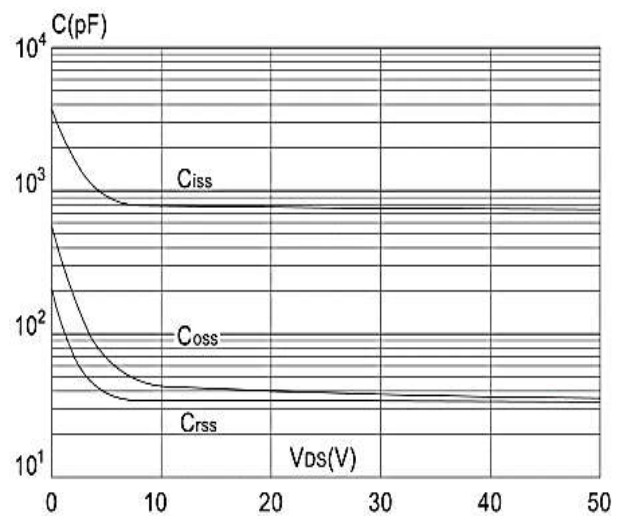


Figure 6: Capacitance Characteristics

Ratings and Characteristic Curves

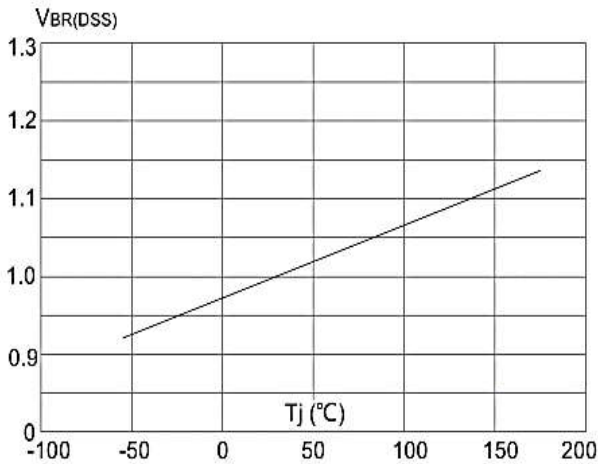


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

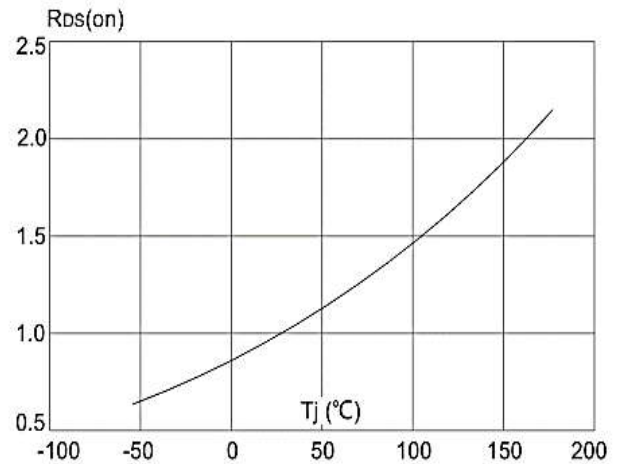


Figure 8: Normalized on Resistance vs. Junction Temperature

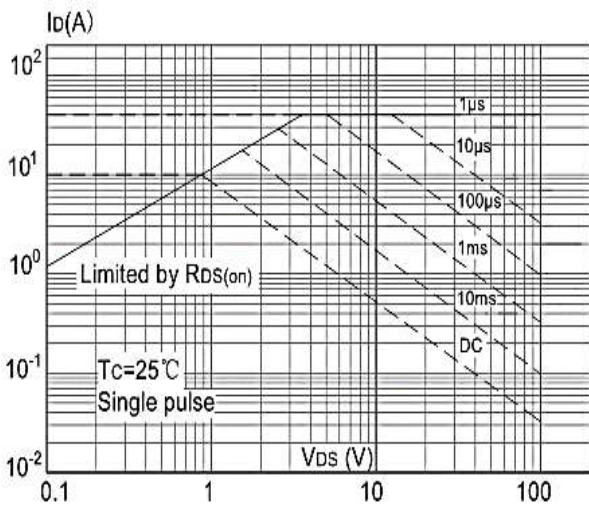


Figure 9: Maximum Safe Operating Area

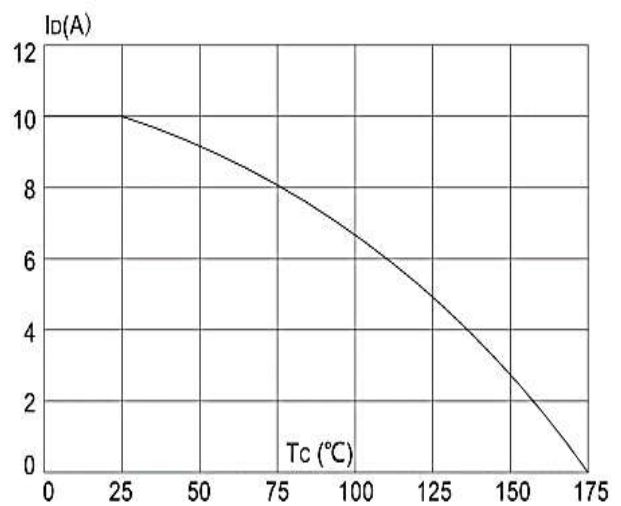


Figure 10: Maximum Continuous Drain Current vs. Case Temperature

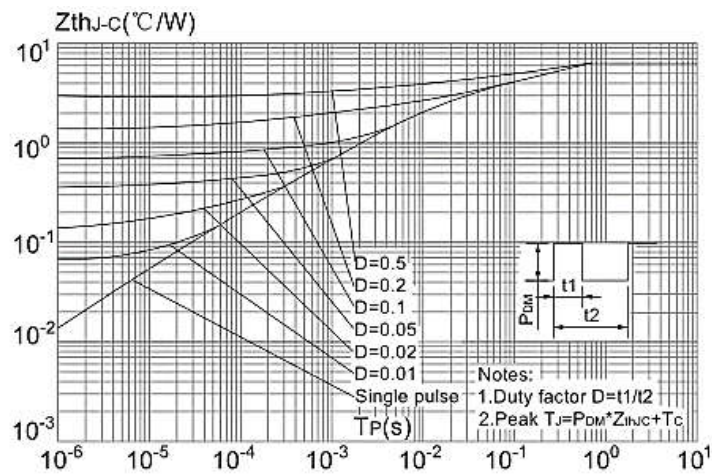
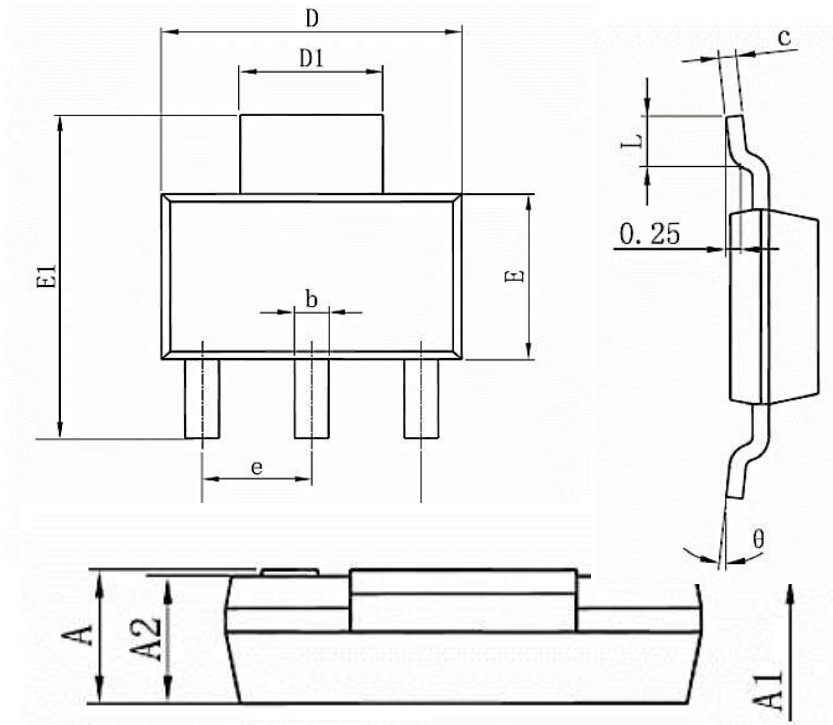


Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Case

SOT-223



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.52	1.8	0.06	0.049
A1	0.000	0.100	0.000	0.004
A2	1.5	1.7	0.059	0.045
b	0.66	0.82	0.026	0.032
c	0.25	0.35	0.010	0.014
D	6.2	6.4	0.244	0.252
D1	2.9	3.1	0.114	0.122
E	3.3	3.7	0.130	0.146
E1	6.83	7.07	0.269	0.278
e	2.300(BSC)		0.037(BSC)	
e1	4.500	4.700	0.177	0.185
L	0.900	1.15	0.035	0.045
θ	0°	10°	0°	10°